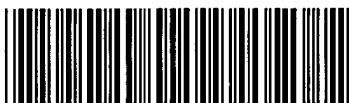


Search Notes

Application No.

10/649,123

Examiner

Stephen W. Smoot

Applicant(s)

KATZ, ANNE T.

Art Unit

2813

SEARCHED

Class	Subclass	Date	Examiner
257	686	3/3/2004	SWS
257	697	3/3/2004	SWS
257	723	3/3/2004	SWS
257	725	3/3/2004	SWS
257	777	3/3/2004	SWS
257	784	3/3/2004	SWS
257	789	3/3/2004	SWS
257	795	3/3/2004	SWS
438	109	3/3/2004	SWS

*S.W.S.***INTERFERENCE SEARCHED**

Class	Subclass	Date	Examiner

**SEARCH NOTES
(INCLUDING SEARCH STRATEGY)**

	DATE	EXMR
Considered all references cited in parent application.	3/3/2004	<i>S.W.S.</i> SWS
Key Words: Package Substrate, Wiring Substrate, ChipCarrier, Multichip Module -MCM;	3/3/2004	<i>S.W.S.</i> SWS
COC - Chip-on-Chip, Chip-Over-Chip, Stacked Chip;	3/3/2004	<i>S.W.S.</i> SWS
Encapsulant, Adhesive, Silver-Filled, Tape; Wire Bonding, Bond Wires	3/3/2004	<i>S.W.S.</i> SWS
Search Tools - EAST (attached): USPAT; US PG PUBS; Derwent; EPO; JPO; IBM TDB	3/3/2004	<i>S.W.S.</i> SWS